

ABSTRACT

The disclosure relates to a conductive paste comprising the following components (A) to (C):

component (A): an epoxy resin;

5 component (B): a latent curing agent; and

component (C): a plate-like crystalline metal powder having an average particle diameter of 0.6 to 1.4 μm .

According to the present invention, there is provided a conductive paste that can achieve both conductivity and adhesive
10 strength in resulting cured product.

No Figure.